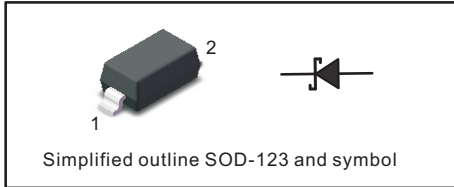


PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



Surface Mount Zener Diodes

FEATURES

- ◆ Total power dissipation: Max. 500mW.
- ◆ Wide zener reverse voltage range 2.0 V to 39V.
- ◆ Small plastic package suitable for surface mounted design.

MECHANICAL DATA

- ◆ Case: SOD-123
- ◆ Terminals: Solderable per MIL-STD-750, Method 2026
- ◆ Approx. Weight: 16mg 0.00056oz

Absolute Maximum Ratings And Characteristics (Ta = 25 °C)

Parameter	Symbol	Value	Unit
Power Dissipation	P_D	500	mW
Forward Voltage at $I_F = 10$ mA	V_F	0.9	V
Typical thermal resistance junction to ambient ⁽¹⁾	$R_{\theta JA}$	305	°C/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	°C

(1) Thermal resistance from junction to ambient at P.C.B. mounted with 7.6mm X 9.4mm X 0.87mm copper areas pads.

Fig.1 Maximum Continuous Power Derating

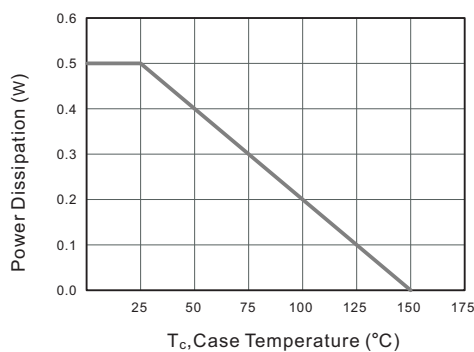
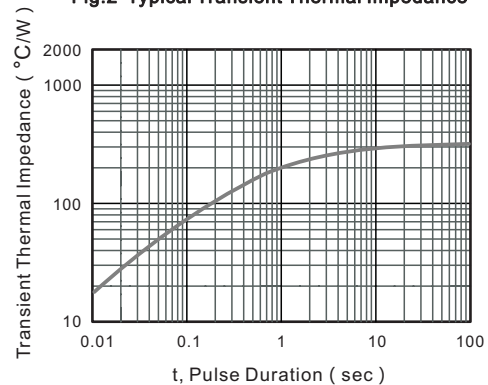


Fig.2 Typical Transient Thermal Impedance



Characteristics at Ta = 25°C

Type	Marking	Zener Voltage Range ⁽²⁾				Maximum Zener ⁽³⁾ Impedance			Reverse Current ⁽²⁾		Typical temperature coefficient @I _{ZTC} mV/°C		Test current I _{ZTC} mA
		V _{ZT} (at I _{ZT})			I _{ZT}	Z _{ZT} @I _{ZT}	Z _{ZK} @I _{ZK}	I _{ZK}	I _R	@V _R	MIN	MAX	
		Min (V)	Nom (V)	Max (V)	(mA)	(Ω)	(mA)	μA	V				
BZT52C2V0	WY	1.91	2.0	2.09	5	100	600	1	150	1.0	-3.5	0	5
BZT52C2V4	WX	2.2	2.4	2.6	5	100	600	1	50	1.0	-3.5	0	5
BZT52C2V7	W1	2.5	2.7	2.9	5	100	600	1	20	1.0	-3.5	0	5
BZT52C3V0	W2	2.8	3.0	3.2	5	95	600	1	10	1.0	-3.5	0	5
BZT52C3V3	W3	3.1	3.3	3.5	5	95	600	1	5.0	1.0	-3.5	0	5
BZT52C3V6	W4	3.4	3.6	3.8	5	90	600	1	5.0	1.0	-3.5	0	5
BZT52C3V9	W5	3.7	3.9	4.1	5	90	600	1	3.0	1.0	-3.5	0	5
BZT52C4V3	W6	4.0	4.3	4.6	5	90	600	1	3.0	1.0	-3.5	0	5
BZT52C4V7	W7	4.4	4.7	5.0	5	80	500	1	3.0	2.0	-3.5	0.2	5
BZT52C5V1	W8	4.8	5.1	5.4	5	60	480	1	2.0	2.0	-2.7	1.2	5
BZT52C5V6	W9	5.2	5.6	6.0	5	40	400	1	1.0	2.0	-2	2.5	5
BZT52C6V2	WA	5.8	6.2	6.6	5	10	150	1	3.0	4.0	0.4	3.7	5
BZT52C6V8	WB	6.4	6.8	7.2	5	15	80	1	2.0	4.0	1.2	4.5	5
BZT52C7V5	WC	7.0	7.5	7.9	5	15	80	1	1.0	5.0	2.5	5.3	5
BZT52C8V2	WD	7.7	8.2	8.7	5	15	80	1	0.7	5.0	3.2	6.2	5
BZT52C9V1	WE	8.5	9.1	9.6	5	15	100	1	0.5	6.0	3.8	7.0	5
BZT52C10	WF	9.4	10	10.6	5	20	150	1	0.2	7.0	4.5	8.0	5
BZT52C11	WG	10.4	11	11.6	5	20	150	1	0.1	8.0	5.4	9.0	5
BZT52C12	WH	11.4	12	12.7	5	25	150	1	0.1	8.0	6.0	10.0	5
BZT52C13	WI	12.4	13	14.1	5	30	170	1	0.1	8.0	7.0	11.0	5
BZT52C15	WJ	13.8	15	15.6	5	30	200	1	0.1	10.5	9.2	13.0	5
BZT52C16	WK	15.3	16	17.1	5	40	200	1	0.1	11.2	10.4	14.0	5
BZT52C18	WL	16.8	18	19.1	5	45	225	1	0.1	12.6	12.4	16.0	5
BZT52C20	WM	18.8	20	21.2	5	55	225	11	0.1	14.0	14.4	18.0	5
BZT52C22	WN	20.8	22	23.3	5	55	250	1	0.1	15.4	16.4	20.0	5
BZT52C24	WO	22.8	24	25.6	5	70	250	1	0.1	16.8	18.4	22.0	5
BZT52C27	WP	25.1	27	28.9	2	80	300	0.5	0.1	18.9	21.4	25.3	2
BZT52C30	WQ	28.0	30	32.0	2	80	300	0.5	0.1	21.0	24.4	29.4	2
BZT52C33	WR	31.0	33	35.0	2	80	325	0.5	0.1	23.1	27.4	33.4	2
BZT52C36	WS	34.0	36	38.0	2	90	350	0.5	0.1	25.2	30.4	37.4	2
BZT52C39	WT	37.0	39	41.0	2	130	350	0.5	0.1	27.3	33.4	41.2	2
BZT52C43	WU	40.0	43	46.0	2	100	700	1	0.1	32.0	10.0	12.0	5

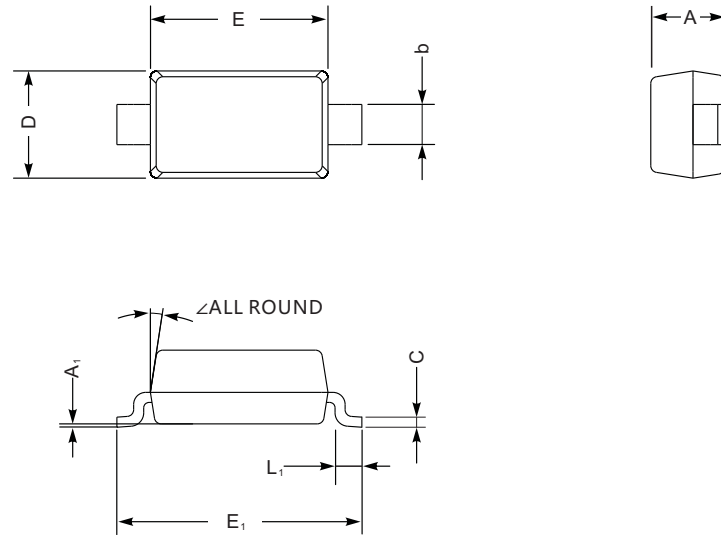
NOTES: (1) f=1KHz

(2) Short duration test pulse used to minimize self-heating effect.

PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD-123



SOD-123 mechanical data

UNIT		A	C	D	E	E ₁	L ₁	b	A ₁	∠
mm	max	1.3	0.22	1.8	2.8	3.9	0.45	0.7	0.2	9°
	min	0.9	0.09	1.5	2.5	3.6	0.25	0.5	—	
mil	max	51	8.7	71	110	154	18	28	8	
	min	35	3.5	59	98	142	10	20	—	

The recommended mounting pad size

